

NTB6413AN, NTP6413AN, NVB6413AN



ON Semiconductor®

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MOSFET – Power, N-Channel 100 V, 42 A, 28 mΩ

Features

- Low $R_{DS(on)}$
- High Current Capability
- 100% Avalanche Tested
- NVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ Unless otherwise specified)

| Parameter | | | Symbol | Value | Unit |
|---|------------------------|---------------------------|----------------|-------------|------------------|
| Drain-to-Source Voltage | | | V_{DS} | 100 | V |
| Gate-to-Source Voltage – Continuous | | | V_{GS} | ± 20 | V |
| Continuous Drain Current $R_{\theta JC}$ | Steady State | $T_C = 25^\circ\text{C}$ | I_D | 42 | A |
| | | $T_C = 100^\circ\text{C}$ | | 28 | |
| Power Dissipation $R_{\theta JC}$ | Steady State | $T_C = 25^\circ\text{C}$ | P_D | 136 | W |
| Pulsed Drain Current | $t_p = 10 \mu\text{s}$ | | I_{DM} | 178 | A |
| Operating Junction and Storage Temperature Range | | | T_J, T_{stg} | -55 to +175 | $^\circ\text{C}$ |
| Source Current (Body Diode) | | | I_S | 42 | A |
| Single Pulse Drain-to-Source Avalanche Energy ($V_{DD} = 50 \text{ Vdc}$, $V_{GS} = 10 \text{ Vdc}$, $I_{L(pk)} = 36.5 \text{ A}$, $L = 0.3 \text{ mH}$, $R_G = 25 \Omega$) | | | E_{AS} | 200 | mJ |
| Lead Temperature for Soldering Purposes, 1/8" from Case for 10 Seconds | | | T_L | 260 | $^\circ\text{C}$ |

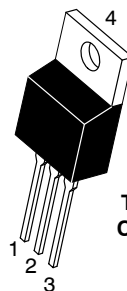
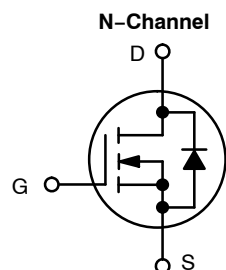
THERMAL RESISTANCE RATINGS

| Parameter | Symbol | Max | Unit |
|---------------------------------------|-----------------|-----|--------------------|
| Junction-to-Case (Drain) Steady State | $R_{\theta JC}$ | 1.1 | $^\circ\text{C/W}$ |
| Junction-to-Ambient (Note 1) | $R_{\theta JA}$ | 35 | |

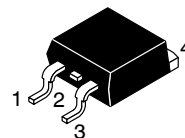
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Surface mounted on FR4 board using 1 sq in pad size, (Cu Area 1.127 sq in [2 oz] including traces).

| $V_{(BR)DSS}$ | $R_{DS(ON)} \text{ MAX}$ | $I_D \text{ MAX}$ (Note 1) |
|---------------|--------------------------|-------------------------------|
| 100 V | 28 mΩ @ 10 V | 42 A |

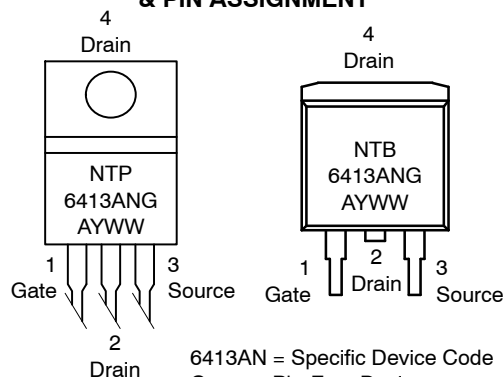


TO-220AB
CASE 221A
STYLE 5



D²PAK
CASE 418B
STYLE 2

MARKING DIAGRAM & PIN ASSIGNMENT



6413AN = Specific Device Code
G = Pb-Free Device
A = Assembly Location
Y = Year
WW = Work Week

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

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ELECTRICAL CHARACTERISTICS (T_J = 25°C Unless otherwise specified)

| Characteristics | Symbol | Test Condition | Min | Typ | Max | Unit |
|-----------------|--------|----------------|-----|-----|-----|------|
|-----------------|--------|----------------|-----|-----|-----|------|

OFF CHARACTERISTICS

| | | | | | | |
|---|--------------------------------------|---|------------------------|-----|------|-------|
| Drain-to-Source Breakdown Voltage | V _{(BR)DSS} | V _{GS} = 0 V, I _D = 250 μA | 100 | | | V |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | V _{(BR)DSS} /T _J | | | 115 | | mV/°C |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{GS} = 0 V, V _{DS} = 100 V | T _J = 25°C | | 1.0 | μA |
| | | | T _J = 125°C | | 100 | |
| Gate-to-Source Leakage Current | I _{GSS} | V _{DS} = 0 V, V _{GS} = ±20 V | | | ±100 | nA |

ON CHARACTERISTICS (Note 2)

| | | | | | | |
|--|-------------------------------------|---|-----|------|-----|-------|
| Gate Threshold Voltage | V _{GS(th)} | V _{GS} = V _{DS} , I _D = 250 μA | 2.0 | | 4.0 | V |
| Negative Threshold Temperature Coefficient | V _{GS(th)} /T _J | | | 8.1 | | mV/°C |
| Drain-to-Source On-Resistance | R _{DS(on)} | V _{GS} = 10 V, I _D = 42 A | | 25.6 | 28 | mΩ |
| Forward Transconductance | g _{FS} | V _{GS} = 5 V, I _D = 20 A | | 17.9 | | S |

CHARGES, CAPACITANCES & GATE RESISTANCE

| | | | | | | |
|------------------------------|---------------------|--|--|------|--|----|
| Input Capacitance | C _{iss} | V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz | | 1800 | | pF |
| Output Capacitance | C _{oss} | | | 280 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 100 | | |
| Total Gate Charge | Q _{G(TOT)} | V _{GS} = 10 V, V _{DS} = 80 V, I _D = 42 A | | 51 | | nC |
| Threshold Gate Charge | Q _{G(TH)} | | | 2.0 | | |
| Gate-to-Source Charge | Q _{GS} | | | 10 | | |
| Gate-to-Drain Charge | Q _{GD} | | | 26 | | |
| Plateau Voltage | V _{GP} | | | 5.8 | | |
| Gate Resistance | R _G | | | 2.4 | | Ω |

SWITCHING CHARACTERISTICS, V_{GS} = 10 V (Note 3)

| | | | | | | |
|---------------------|---------------------|--|--|----|--|----|
| Turn-On Delay Time | t _{d(on)} | V _{GS} = 10 V, V _{DD} = 80 V, I _D = 42 A, R _G = 6.2 Ω | | 13 | | ns |
| Rise Time | t _r | | | 84 | | |
| Turn-Off Delay Time | t _{d(off)} | | | 52 | | |
| Fall Time | t _f | | | 71 | | |

DRAIN-SOURCE DIODE CHARACTERISTICS

| | | | | | | | |
|-------------------------|-----------------|--|------------------------|-----|------|-----|----|
| Forward Diode Voltage | V _{SD} | I _S = 42 A | T _J = 25°C | | 0.92 | 1.3 | V |
| | | | T _J = 125°C | | 0.83 | | |
| Reverse Recovery Time | t _{rr} | V _{GS} = 0 V, I _S = 42 A, dI _{SD} /dt = 100 A/μs | | 73 | | ns | |
| Charge Time | t _a | | | 56 | | | |
| Discharge Time | t _b | | | 17 | | | |
| Reverse Recovery Charge | Q _{RR} | | | 230 | | | nC |

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
3. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

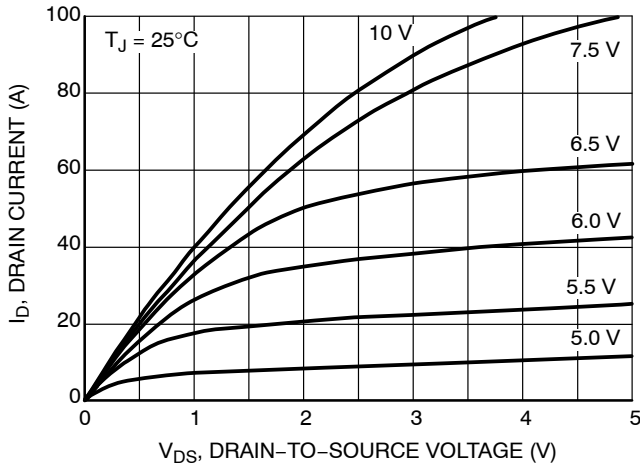


Figure 1. On-Region Characteristics

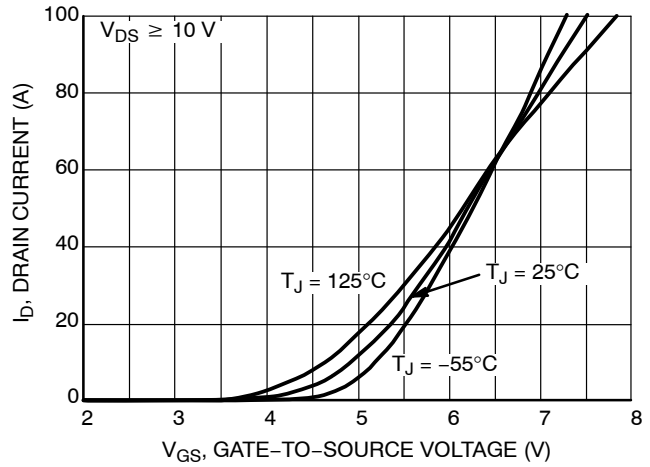


Figure 2. Transfer Characteristics

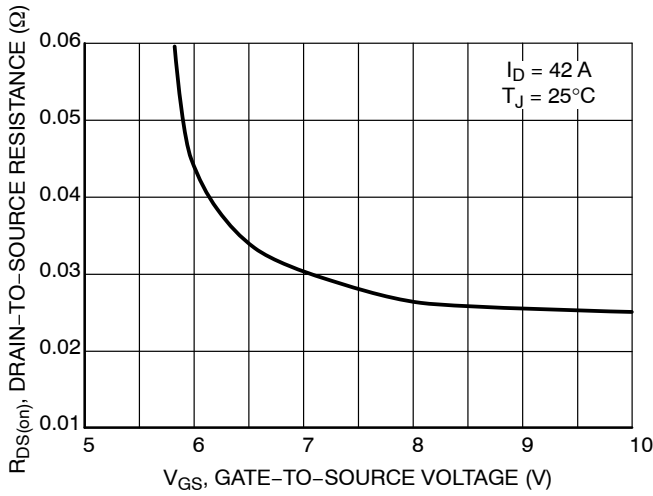


Figure 3. On-Region versus Gate Voltage

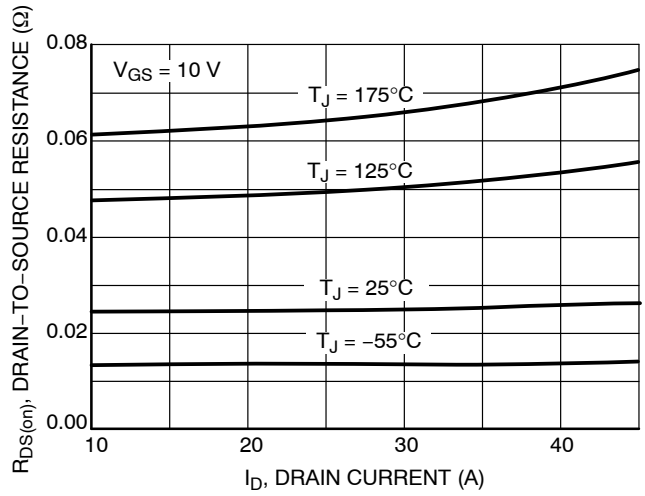


Figure 4. On-Resistance versus Drain Current and Gate Voltage

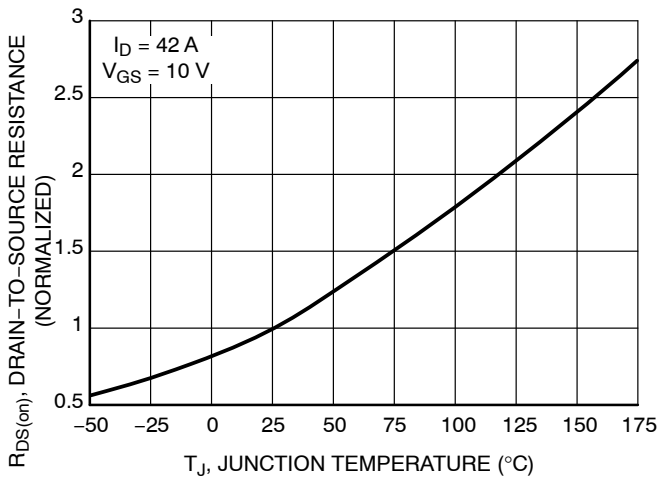


Figure 5. On-Resistance Variation with Temperature

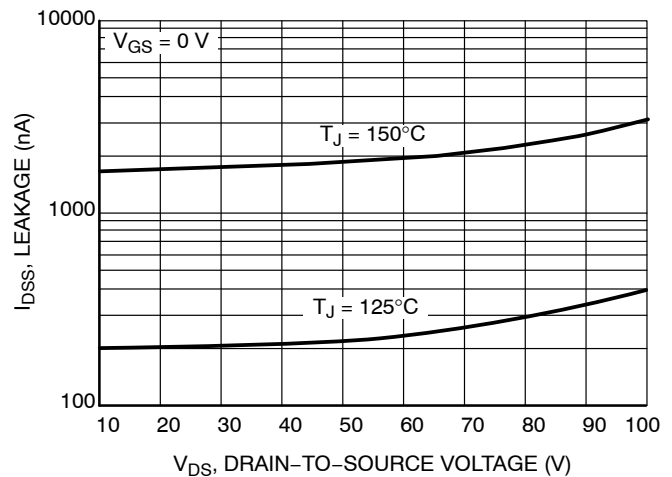


Figure 6. Drain-to-Source Leakage Current versus Voltage

TYPICAL CHARACTERISTICS

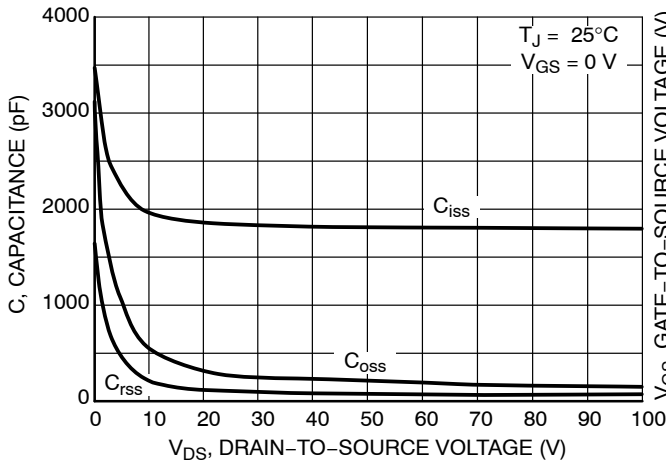


Figure 7. Capacitance Variation

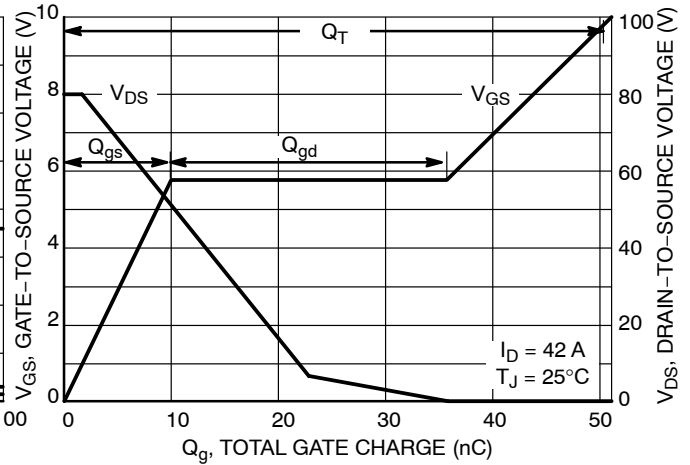


Figure 8. Gate-to-Source Voltage and Drain-to-Source Voltage versus Total Charge

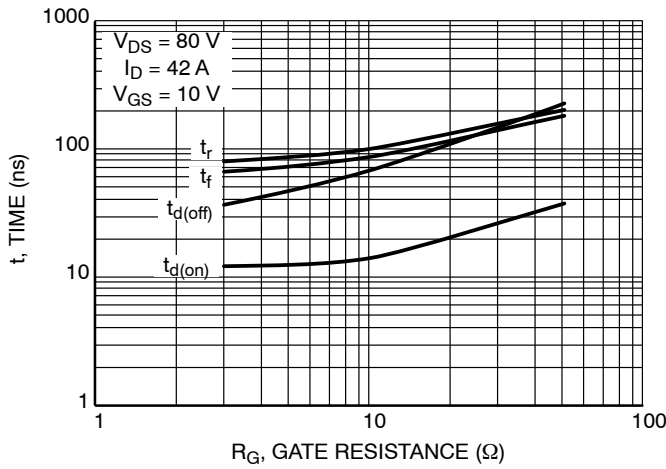


Figure 9. Resistive Switching Time Variation versus Gate Resistance

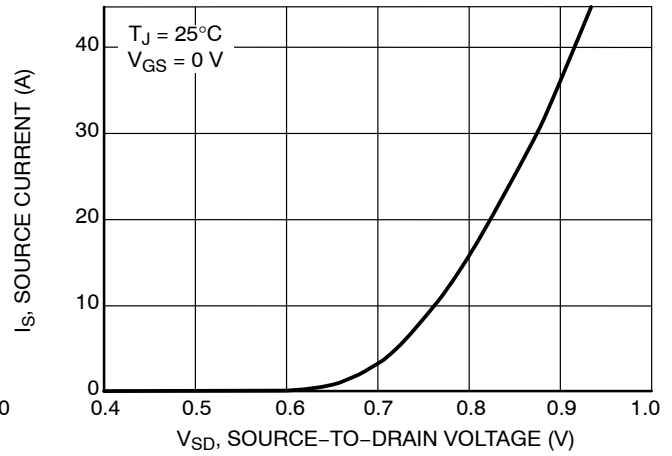


Figure 10. Diode Forward Voltage versus Current

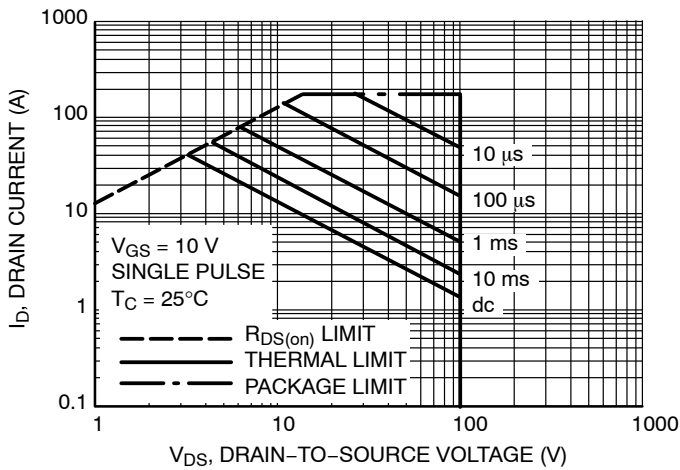


Figure 11. Maximum Rated Forward Biased Safe Operating Area

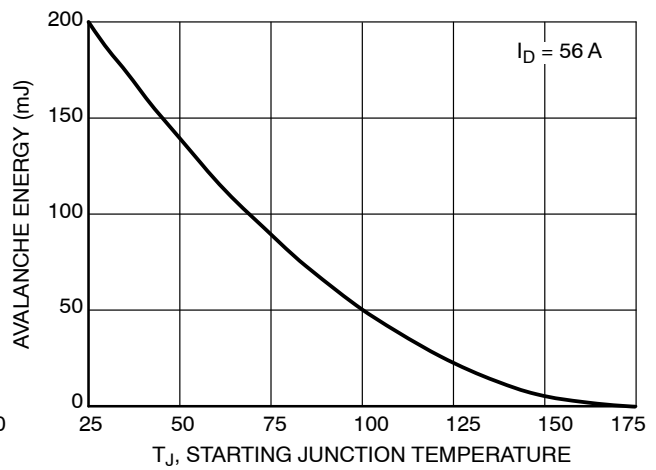


Figure 12. Maximum Avalanche Energy versus Starting Junction Temperature

NTB6413AN, NTP6413AN, NVB6413AN

TYPICAL CHARACTERISTICS

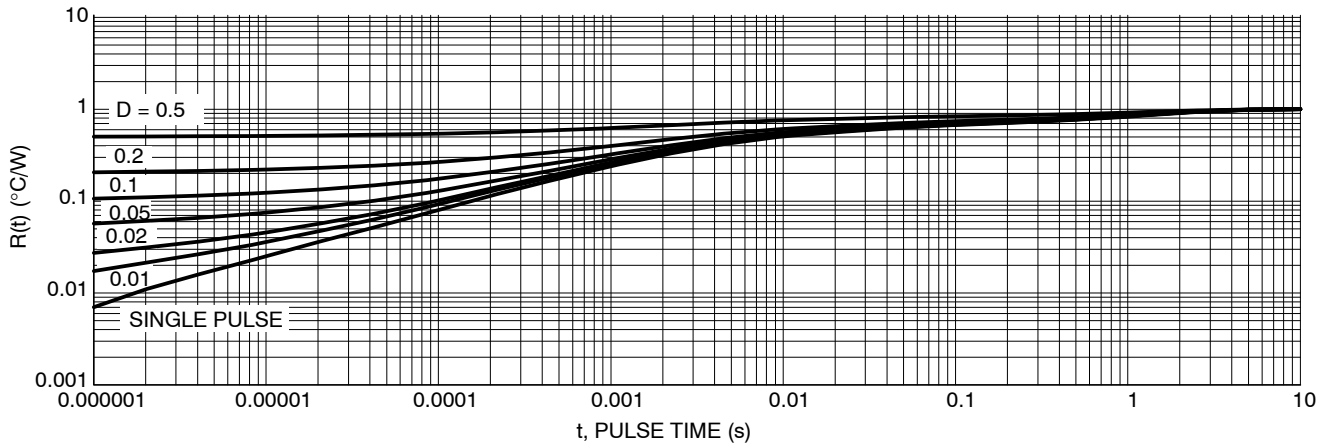


Figure 13. Thermal Response

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|--------------|---------------------------------|-----------------------|
| NTB6413ANG | D ² PAK (Pb-Free) | 50 Units / Rail |
| NTB6413ANT4G | D ² PAK (Pb-Free) | 800 / Tape & Reel |
| NTP6413ANG | TO-220 (Pb-Free) | 50 Units / Rail |
| NVB6413ANT4G | D ² PAK (Pb-Free) | 800 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

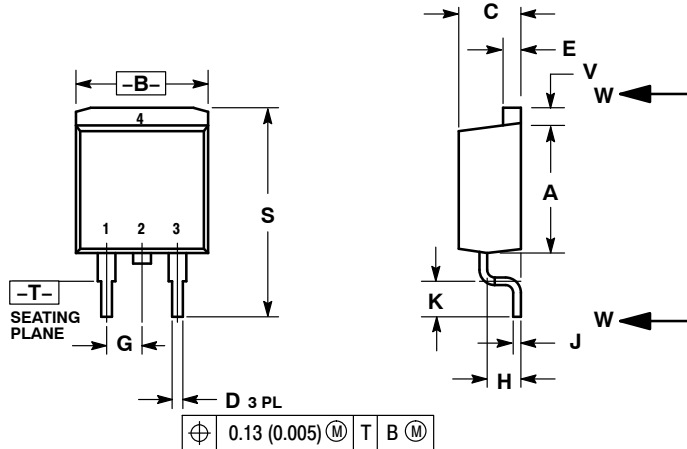
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D²PAK 3
CASE 418B-04
ISSUE L

DATE 17 FEB 2015

SCALE 1:1

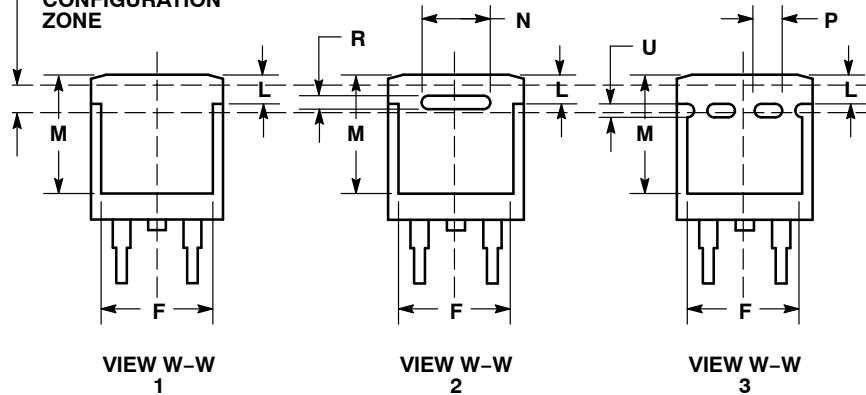


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.340 | 0.380 | 8.64 | 9.65 |
| B | 0.380 | 0.405 | 9.65 | 10.29 |
| C | 0.160 | 0.190 | 4.06 | 4.83 |
| D | 0.020 | 0.035 | 0.51 | 0.89 |
| E | 0.045 | 0.055 | 1.14 | 1.40 |
| F | 0.310 | 0.350 | 7.87 | 8.89 |
| G | 0.100 | BSC | 2.54 | BSC |
| H | 0.080 | 0.110 | 2.03 | 2.79 |
| J | 0.018 | 0.025 | 0.46 | 0.64 |
| K | 0.090 | 0.110 | 2.29 | 2.79 |
| L | 0.052 | 0.072 | 1.32 | 1.83 |
| M | 0.280 | 0.320 | 7.11 | 8.13 |
| N | 0.197 | REF | 5.00 | REF |
| P | 0.079 | REF | 2.00 | REF |
| R | 0.039 | REF | 0.99 | REF |
| S | 0.575 | 0.625 | 14.60 | 15.88 |
| V | 0.045 | 0.055 | 1.14 | 1.40 |

VARIABLE CONFIGURATION ZONE



- | | | | | | |
|--|---|---|--|---|--|
| STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR | STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN | STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE | STYLE 4: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR | STYLE 5: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE | STYLE 6: PIN 1. NO CONNECT 2. CATHODE 3. ANODE 4. CATHODE |
|--|---|---|--|---|--|

MARKING INFORMATION AND FOOTPRINT ON PAGE 2

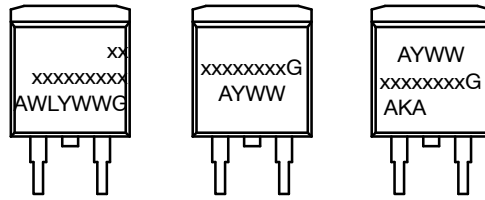
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D²PAK 3
CASE 418B-04
ISSUE L

DATE 17 FEB 2015

**GENERIC
MARKING DIAGRAM***

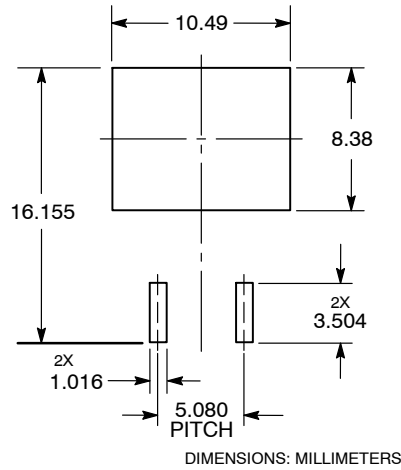


IC Standard Rectifier

- xx = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package
- AKA = Polarity Indicator

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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